

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6037781

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ROHM CO., LTD.	03/26/2020
RECEIVING PARTY DATA	
Name:	BELL SEMICONDUCTOR, LLC
Street Address:	ONE WEST BROAD STREET
City:	BETHLEHEM
State/Country:	PENNSYLVANIA
Postal Code:	18018
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	6624007
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3039182858
Email:	chilyard@hilcoglobal.com
Correspondent Name:	CHAD HILYARD
Address Line 1:	7583 S. XANTHIA COURT
Address Line 4:	CENTENNIAL, COLORADO 80112
NAME OF SUBMITTER:	CHAD HILYARD
SIGNATURE:	/Chad Hilyard/
DATE SIGNED:	03/30/2020
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3	
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ASSIGNMENT

This assignment (“**Assignment**”) is between Rohm Co., Ltd., a company organized under the laws of Japan, with its principal place of business at 21, Saian Mizosaki-Cho, Ukyo-ku, Kyoto, 615-8585, Japan (“**Assignor**”) and Bell Semiconductor, LLC, a Delaware limited liability company, with its principal place of business at One West Broad Street, Bethlehem, PA 18018 (“**Assignee**”).

Assignor owns, all right, title and interest in, to and under the Assigned Patents listed in the Attachment hereto (the “**Assigned Patents**”);

Assignor has agreed to assign all right, title, and interest in, to and under the Assigned Patents to Assignee;

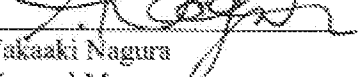
Accordingly, Bell Semic and Rohm agree as follows:

Effective on March 26, 2020, Assignor hereby sells, assigns, transfers, and sets over to Assignee, Assignor’s entire right, title, and interest in, to, and under the Assigned Patents, and all patents, patent applications, foreign patents, foreign patent applications, continuations, continuations-in-part, divisionals, extensions, renewals, reissues and re-examinations that may issue thereon and claim priority to the Assigned Patents, including without limitation, all rights to practice the inventions claimed in the Assigned Patents to the extent that such rights to practice the Assigned Patents do not require, assign, license, transfer, or otherwise implicate (a) any rights to any patent or intellectual property of the Rohm Group other than the Assigned Patents, or (b) any rights to trade secrets or know-how of the Rohm Group, all rights to claim priority on the basis of the Assigned Patents, all rights to sue for past, present and future infringement, including the right to collect and receive any damages, royalties, or settlements for such infringements, all rights to sue for injunctive or other equitable relief, and any and all causes of action relating to any of the inventions or discoveries of the Assigned Patents.

[Signatures on the following page]

Each party is signing this Assignment on the date stated below that party's signature.

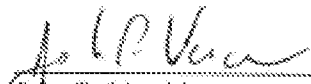
ROHM CO., LTD.

By: 
Name: Takaaki Nagura
Title: General Manager,
Legal & Intellectual Property Division

Date: March 27, 2020

Accepted and Agreed by:

Bell Semiconductor, LLC

By: 
John P. Veschi
CEO
Date: March 30, 2020

Assignment Attachment

Assigned Patents

Family	Patent Number	Country	Title
1	6,624,007	U.S.	<i>Method of Making Leadframe by Mechanical Processing</i>
1	4672201	Japan	<i>Method of Making Leadframe by Mechanical Processing</i>
1	4889169	Japan	<i>Method of Making Leadframe by Mechanical Processing</i>
1	5410465	Japan	<i>Method of Making Leadframe by Mechanical Processing</i>